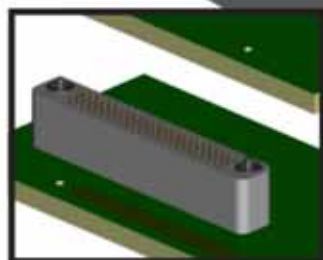
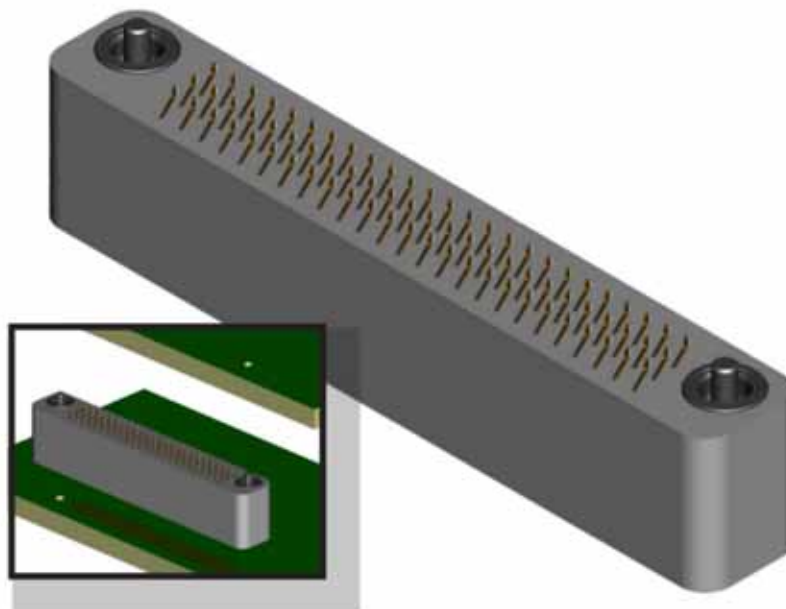




0.05" 1.27mm VERTICAL COMPRESSION (Z-AXIS) LGA CONNECTOR

A high-density LGA (solderless) open-field, vertically-compressed connector utilizing a patented z-axis contact system configured for between-boards compression applications.

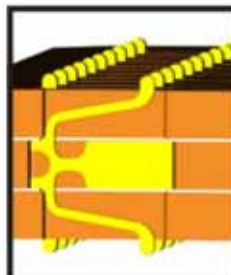


MATERIALS

Contact	BeCu C17200 per ASTM B194 (brush alloy 190)
Contact Finish	Gold per ASTM B488 over nickel per SAE AMS-QQ-N-290
Molded Insulator	Glass-filled polyphenylene sulfide (PPS) per MIL-M-24519
Hardware	Stainless steel per ASTM A582/582M,
.....	Passivated per SAE AMS-2700

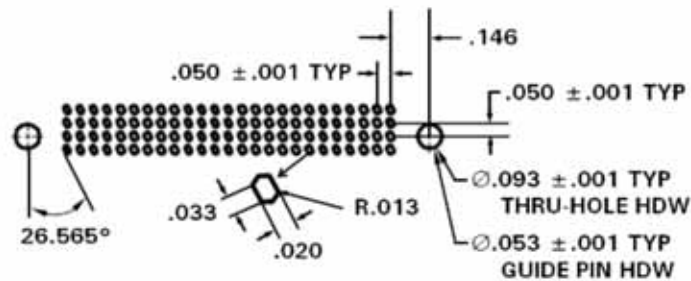
PERFORMANCE

Contact Compression	-0.01"/side (nominal) for 0.100" and 0.150" connector heights
.....	-0.015"/side (nominal) for 0.200", 0.250", 0.300" and 0.350" connector heights
Compression Force	At a nom. of 0.01, compression force is 30 to 40 grams





TYPICAL 0.750" STACK HEIGHT SI PERFORMANCE - BOTH SE and DIF



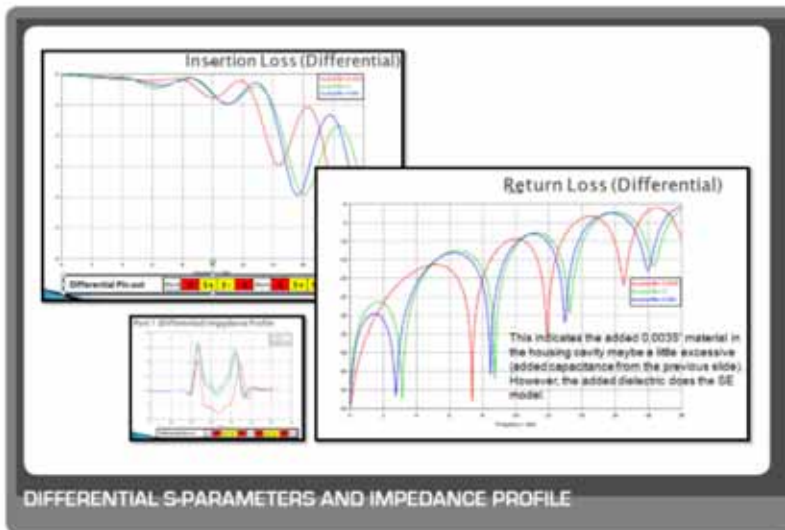
RECOMMENDED BOARD LAYOUT, TYP



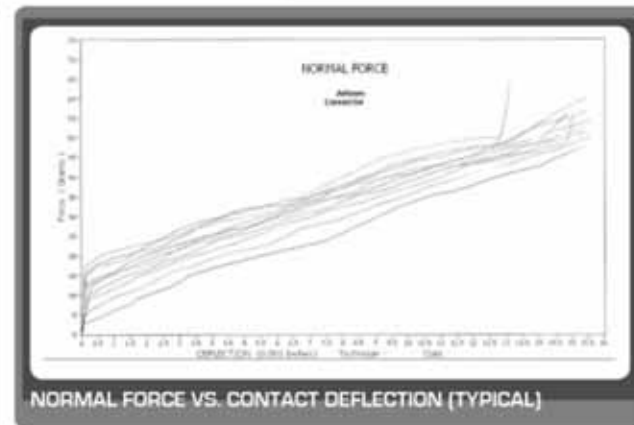
BOARD-TO-BOARD FLEX STACKER



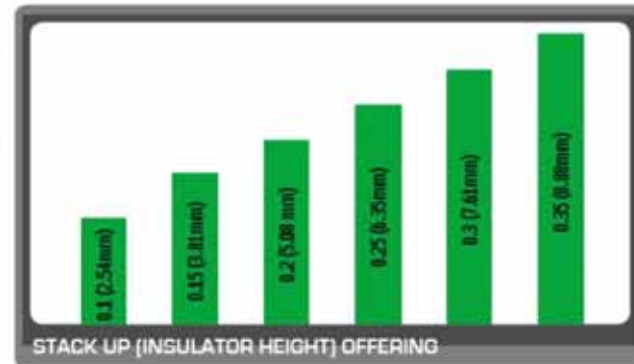
BOARD-TO-BOARD FLEX JUMPER



DIFFERENTIAL S-PARAMETERS AND IMPEDANCE PROFILE



NORMAL FORCE VS. CONTACT DEFLECTION (TYPICAL)



STACK UP (INSULATOR HEIGHT) OFFERING